

### 3.2x1.6mm INFRARED EMITTING DIODE

Part Number: KP-3216F3C

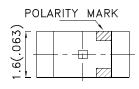
### **Features**

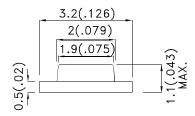
- 3.2mmx1.6mm SMT LED,1.8mm thickness.
- Mechanically and spectrally matched to phototransistor.
- Wide viewing angle.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHs compliant.

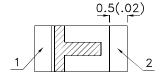
### Description

F3 Made with Gallium Arsenide Infrared Emitting diodes.

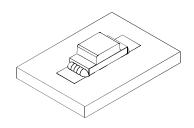
## **Package Dimensions**















- 1. All dimensions are in millimeters (inches).
  2. Tolerance is ±0.2(0.0079") unless otherwise noted.
  3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
  4. The device has a single mounting surface. The device must be mounted according to the specifications.

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### **Selection Guide**

Part No.	Dice	Lens Type	Po (mW/sr) [2] @ 20mA		Viewing Angle [1]
		,,	Min.	Тур.	201/2
KP-3216F3C	F3 (GaAs)	Water Clear	1.2	3	120°
		Water Clear	*0.8	*2	

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Radiant Intensity/ luminous flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Parameter	P/N	Symbol	Тур.	Max.	Units	Test Conditions	
Forward Voltage [1]	F3	VF	1.2	1.6	V	IF=20mA	
Reverse Current	F3	lR		10	uA	V <sub>R</sub> = 5V	
Capacitance	F3	С	90		pF	VF=0V;f=1MHz	
Peak Spectral Wavelength	F3	λP	940		nm	I=20mA	
Spectral Bandwidth	F3	Δλ1/2	50		nm	IF=20mA	

- 1. Forward Voltage: +/-0.1V.
- 2. Wavelength value is traceable to the CIE127-2007 compliant national standards.

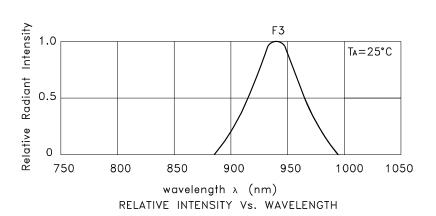
## Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	F3	Units
Power dissipation	Po	80	mW
DC Forward Current	lF	50	mA
Peak Forward Current [1]	iFS	1.2	А
Reverse Voltage	VR	5	V
Operating Temperature	TA	-40 To +85	°C
Storage Temperature	Тѕтс	-40 To +85	°C

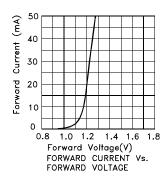
Note: 1. 1/100 Duty Cycle, 10µs Pulse Width.

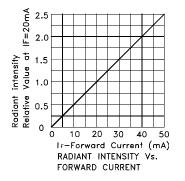
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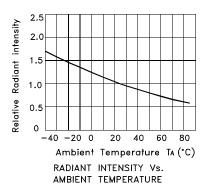
<sup>\*</sup>Radiant intensity value is traceable to the CIE127-2007 compliant national standards.

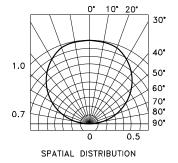


### **KP-3216F3C**









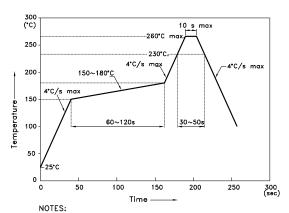
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### **KP-3216F3C**

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



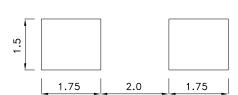
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

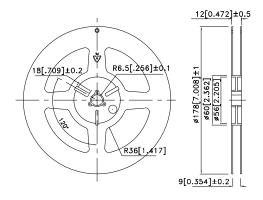
  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

  3.Number of reflow process shall be 2 times or less.

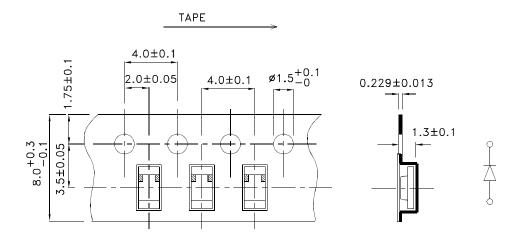
## **Recommended Soldering Pattern** (Units: mm; Tolerance: ± 0.1)



### **Reel Dimension**



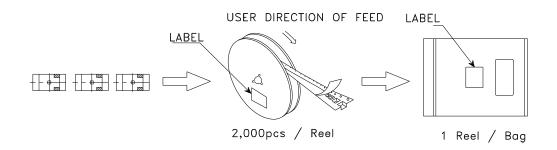
### **Tape Dimensions** (Units: mm)

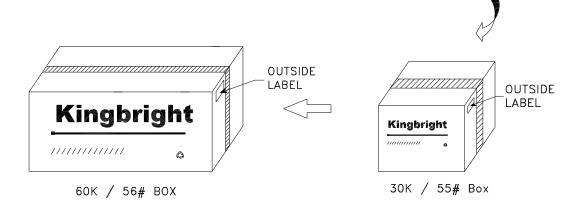


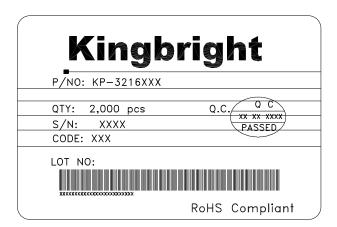
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### **PACKING & LABEL SPECIFICATIONS**

### KP-3216F3C







Detailed application notes are listed on our website. http://www.kingbright.com/application\_notes

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